

**FOR IMMEDIATE RELEASE  
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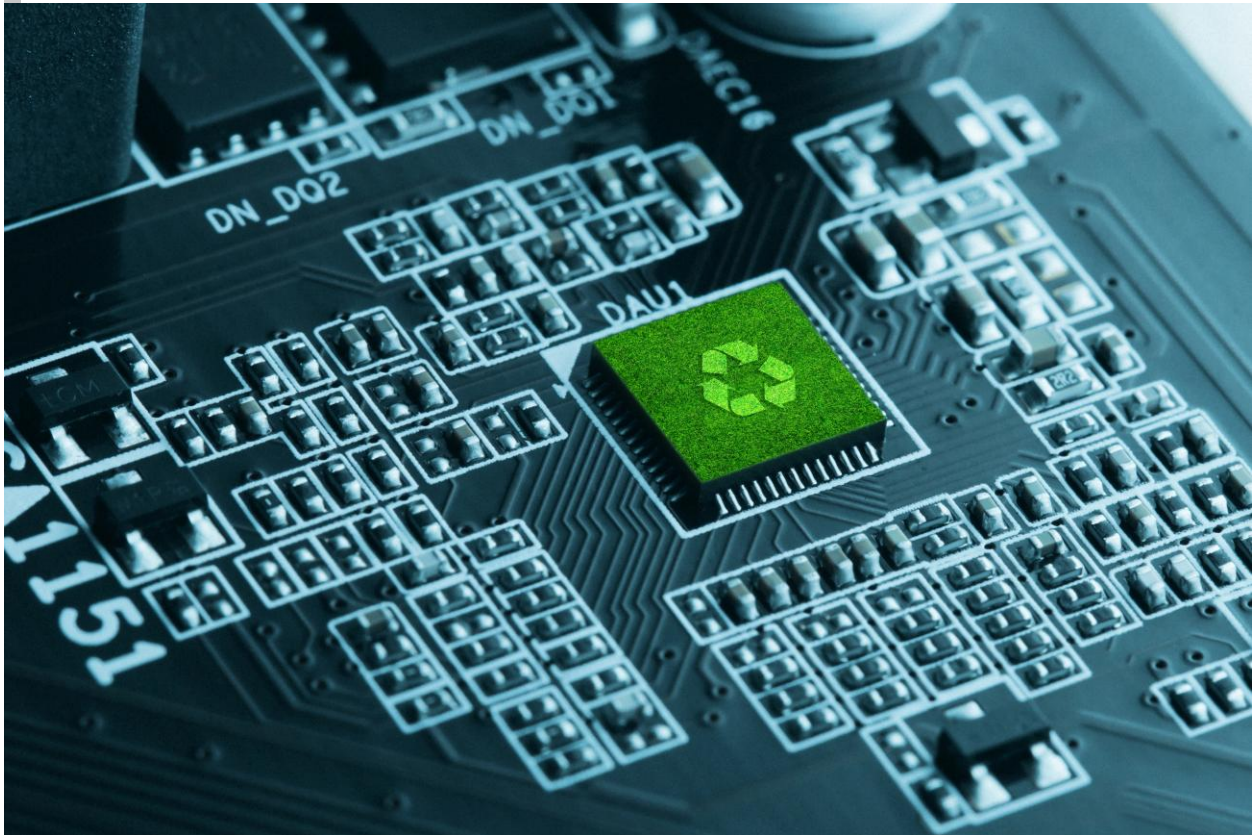
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**PRESS RELEASE**

**MacDermid Alpha Launches ATROX® CD 560-1: Zero PFAS Alternate Silver Filler Die Attach Paste Designed for Cost Stability and High-Speed Production**

**Waterbury, CT – June 18, 2026** – With silver price volatility increasing and sustainability requirements accelerating across semiconductor assembly, MacDermid Alpha Electronics Solutions introduces [ATROX® CD 560-1](#), a zero per- and polyfluoroalkyl substances (PFAS) alternate silver filler die attach paste designed for metal leadframe packages and high-speed automated dispensing in modern manufacturing environments.



As silver prices continue to fluctuate sharply, semiconductor manufacturers face growing pressure on assembly budgets and long-term planning. ATROX CD 560-1 addresses this

challenge through an engineered alternate silver filler approach that supports more stable cost management while delivering reliable performance and production efficiency.

The paste is formulated to support high-speed, high-volume manufacturing, offering 2.5 watts per meter-kelvin (W/mK) bulk thermal conductivity and robust die attach performance across key metal leadframe surfaces, including pre-plated frames (PPF), commonly nickel-palladium-gold (NiPdAu), and copper leadframes. Consistent dispensing performance supports repeatable flow and dispense patterns, along with clean deposits across long production runs with minimal maintenance.

ATROX CD 560-1 is manufactured with no added per- and polyfluoroalkyl substances (PFAS), helping customers respond to evolving environmental expectations and regulatory scrutiny while maintaining device performance. The zero PFAS chemistry aligns with broader sustainability goals without slowing production or adding process complexity.

“This approach sets a new benchmark in conductive die attach by combining manufacturing speed with reliability,” said Avin Dhoble, Product Manager, MacDermid Alpha Electronics Solutions. “It’s tuned dispensing and cure profile supports high-throughput processing, enabling faster production without a quality trade-off.”

The paste is compatible with time-pressure pump systems used on most die bonders, allowing consistent dispensing over long production runs. Low outgassing helps maintain cleaner oven environments and supports strong package reliability in downstream processes. Flexible cure options include snap cure for fast production lines and box-oven cure for conventional manufacturing flows, both delivering consistent results.

By enabling faster operation, lower contamination risk, and improved cost stability, ATROX CD 560-1 expands the ATROX portfolio to address sustainability, throughput, and price stability across semiconductor assembly. The product reflects MacDermid Alpha’s continued commitment to environment, health, and safety (EHS) while maintaining the reliability and build quality required for advanced semiconductor devices.

Evaluate [ATROX CD 560-1](#) on your next leadframe program and request technical data, samples, and a dispensing review from our team.

Discover more via our [website](#)  
Follow us on [Twitter](#) and [LinkedIn](#)

## **ENDS**

### **MacDermid Alpha Electronics Solutions**

MacDermid Alpha Electronics Solutions, a business unit of Element Solutions Inc, is a global leader in high-performance specialty chemicals, materials, and process technologies for every stage of the electronics manufacturing process. With expertise spanning circuitry formation, wafer-level packaging, circuit board assembly, semiconductor assembly, and film and smart surfaces, MacDermid Alpha delivers advanced, sustainable, and integrated solutions that drive innovation and reliability across the electronics supply chain. Operating worldwide and backed by more than a century of innovation, the organization supports a broad range of industries including automotive, consumer electronics, data infrastructure, high-performance computing, and telecommunications enabling next-generation electronics.

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